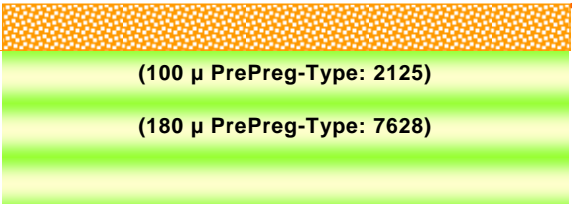
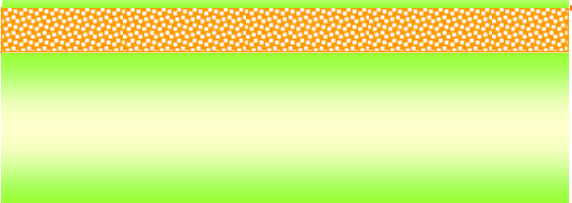
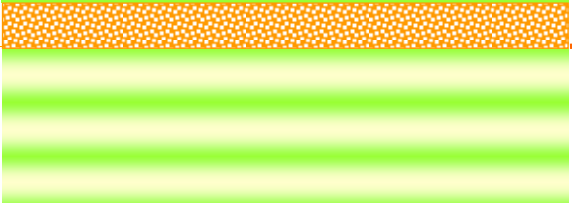



Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
04	190	FR4	35	L110.35	P10_18	s1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_190_FR4_35_L110.35_p10_18_s1

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		A1
	100 μ	Prepreg		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-2	35 μ	Copper		B
	1100 μ	L-FR4		
Layer-3	35 μ	Copper		A1
	180 μ	Prepreg		
	180 μ	Prepreg		
	100 μ	Prepreg		
Layer-99	35 μ	Copper		A1

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